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PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL	NOTES		
84501-001		15µ" (.38µm) Au OVER Ni	SnPb			
84501-001LF	- YES		SnAgCu LEAD FREE	5 & 6		
84501-101		30µ" (.76µm) Au OVER Ni	SnPb			
84501-101LF	- YES		SnAgCu LEAD FREE	5 & 6		
84501-201			SnPb			
84501-201LF	- YES	SEE NOTE 4	SnAgCu LEAD FREE	5&6		
84501-A01		30µ" (.76µm) Au OVER Ni	SnPb			
84501-A01LF	YES	NOTE 7	SnAgCu LEAD FREE	5 & 6		
CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT. (3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE. (4.) PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).			IN THE SEVENTH CHARA (7) 84501-A01 AND -A01L (8) CURRENT COMPANY LOG AREA SHOWN.	LF ARE CUSTC GO TO BE VIS	OMER SPECIALS. SIBLE IN APPROXIMATE	
(5) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.			mal'L code SEE NOTE 1 Itr ecn no dr date L	ASME Y14.5 V A tolerances unless oth angles	Xx3 MM 4mm RECEPTACLE ASSEM   X0Xx651 scale 2:1 10 X 30 = 300 POS   N 7998-12-16 R FC f f f scale 3 of 84501	S. 3 size A4
			sheet revision index sheet			

PDM: Rev:L STATUS:Released Printed: Jun 04, 2011